

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

Drain-to-source Voltage.....	BV_{DSX}
Drain-to-gate Voltage	BV_{DGX}
Gate-to-source Voltage	$\pm 20V$
Operating Ambient Temperature, T_A	$-55^{\circ}C$ to $+150^{\circ}C$
Storage Temperature, T_S	$-55^{\circ}C$ to $+150^{\circ}C$

† **Notice:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS ¹

Electrical Specifications: Unless otherwise specified, for all specifications $T_A = T_J = +25^{\circ}C$.

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
Drain-to-source Breakdown Voltage	BV_{DSX}	350	—	—	V	$V_{GS} = -5V$, $I_D = 100 \mu A$
Gate-to-source Off Voltage	$V_{GS(OFF)}$	-1.5	—	-3.5	V	$V_{DS} = 15V$, $I_D = 10 \mu A$
Change in $V_{GS(OFF)}$ with Temperature	$\Delta V_{GS(OFF)}$	—	—	-4.5	mV/ $^{\circ}C$	$V_{DS} = 15V$, $I_D = 10 \mu A$ (Note 2)
Gate Body Leakage Current	I_{GSS}	—	—	100	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$
Drain-to-source Leakage Current	$I_{D(OFF)}$	—	—	1	μA	$V_{DS} = \text{Max rating}$, $V_{GS} = -5V$
		—	—	1	mA	$V_{DS} = 0.8 \text{ Max Rating}$, $V_{GS} = -5V$, $T_A = 125^{\circ}C$ (Note 2)
Saturated Drain-to-source Current	I_{DSS}	180	—	—	mA	$V_{GS} = 0V$, $V_{DS} = 15V$
Static Drain-to-source On-state Resistance	$R_{DS(ON)}$	—	—	35	Ω	$V_{GS} = 0V$, $I_D = 150 \text{ mA}$
Change in $R_{DS(ON)}$ with Temperature	$\Delta R_{DS(ON)}$	—	—	1.1	%/ $^{\circ}C$	$V_{GS} = 0V$, $I_D = 150 \text{ mA}$ (Note 2)

Note 1: All DC parameters are 100% tested at $25^{\circ}C$ unless otherwise stated. Pulse test: 300 μs pulse, 2% duty cycle.

2: Specification is obtained by characterization and is not 100% tested.

AC ELECTRICAL CHARACTERISTICS ²

Electrical Specifications: Unless otherwise specified, for all specifications T _A =T _J = +25°C.						
Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
Forward Transconductance	G _{FS}	140	—	—	mmho	V _{DS} = 10V, I _D = 100 mA
Input Capacitance	C _{ISS}	—	60	120	pF	V _{GS} = −5V, V _{DS} = 25V, f = 1 MHz
Common Source Output Capacitance	C _{OSS}	—	6	15		
Reverse Transfer Capacitance	C _{RSS}	—	3	10		
Turn-on Delay Time	t _{d(ON)}	—	—	10	ns	V _{DD} = 25V, I _D = 150 mA, R _{GEN} = 25Ω, V _{GS} = 0V to −10V
Rise Time	t _r	—	—	15		
Turn-off Delay Time	t _{d(OFF)}	—	—	15		
Fall Time	t _f	—	—	20		
DIODE PARAMETER						
Diode Forward Voltage Drop	V _{SD}	—	—	1.8	V	V _{GS} = −5V, I _{SD} = 150 mA (Note 1)
Reverse Recovery Time	t _{rr}	—	800	—	ns	V _{GS} = −5V, I _{SD} = 150 mA (Note 2)

Note 1: All DC parameters are 100% tested at 25°C unless otherwise stated. Pulse test: 300 μs pulse, 2% duty cycle.

2: Specification is obtained by characterization and is not 100% tested.

TEMPERATURE SPECIFICATIONS

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
TEMPERATURE RANGE						
Operating Ambient Temperature	T_A	-55	—	+150	$^\circ\text{C}$	
Storage Temperature	T_S	-55	—	+150	$^\circ\text{C}$	
PACKAGE THERMAL RESISTANCE						
SOT-23	θ_{JA}	—	203	—	$^\circ\text{C/W}$	
SOT-89	θ_{JA}	—	133	—	$^\circ\text{C/W}$	

THERMAL CHARACTERISTICS

Package	$I_D^{(1)}$ (Continuous) (mA)	I_D (Pulsed) (mA)	Power Dissipation at $T_A = 25^\circ\text{C}$ (W)	$I_{DR}^{(1)}$ (mA)	I_{DRM} (mA)
SOT-23	72	300	0.36	72	300
SOT-89	135	300	1.3 ⁽²⁾	135	300

Note 1: I_D (continuous) is limited by maximum T_J .

2: Mounted on FR4 board, 25 mm x 25 mm x 1.57 mm

DN3135

2.0 PIN DESCRIPTION

Table 2-1 shows the description of pins in DN3135 SOT-23 and SOT-89. Refer to [Package Types](#) for the location of pins.

TABLE 2-1: PIN FUNCTION TABLE

SOT-23 Pin Number	SOT-89 Pin Number	Pin Name	Description
1	1	Gate	Gate
2	3	Source	Source
3	2, 4	Drain	Drain

3.0 FUNCTIONAL DESCRIPTION

Figure 3-1 illustrates the switching waveforms and test circuit for DN3135.

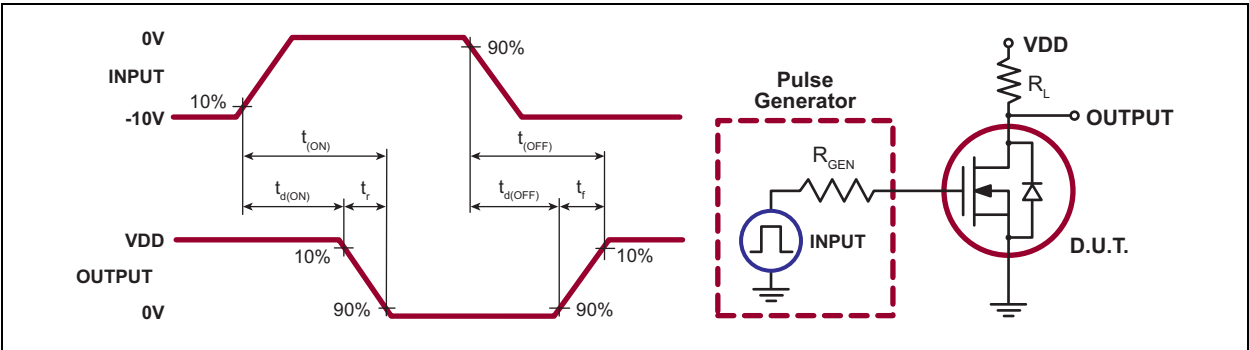


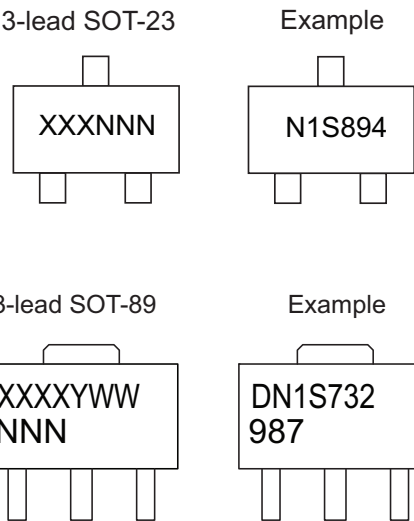
FIGURE 3-1: Switching Waveforms and Test Circuit.

PRODUCT SUMMARY

BV_{DSX}/BV_{DGX} (V)	$R_{DS(ON)}$ (Maximum) (Ω)	I_{DSS} (Minimum) (mA)
350	35	180

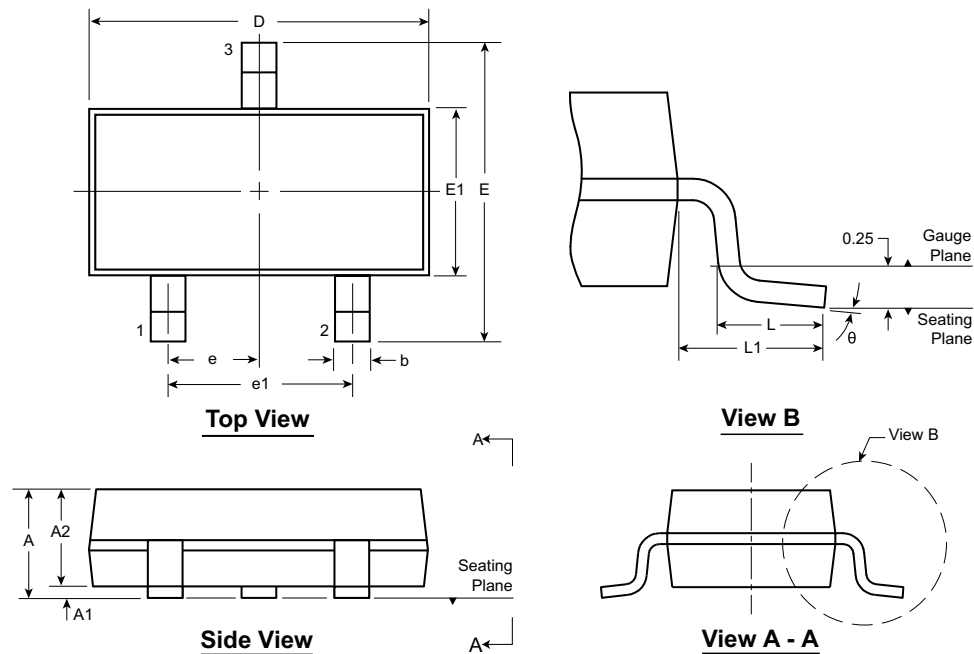
4.0 PACKAGING INFORMATION

4.1 Package Marking Information



Legend:	XX...X	Product Code or Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for product code or customer-specific information. Package may or not include the corporate logo.		

3-Lead TO-236AB (SOT-23) Package Outline (K1/T) 2.90x1.30mm body, 1.12mm height (max), 1.90mm pitch



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

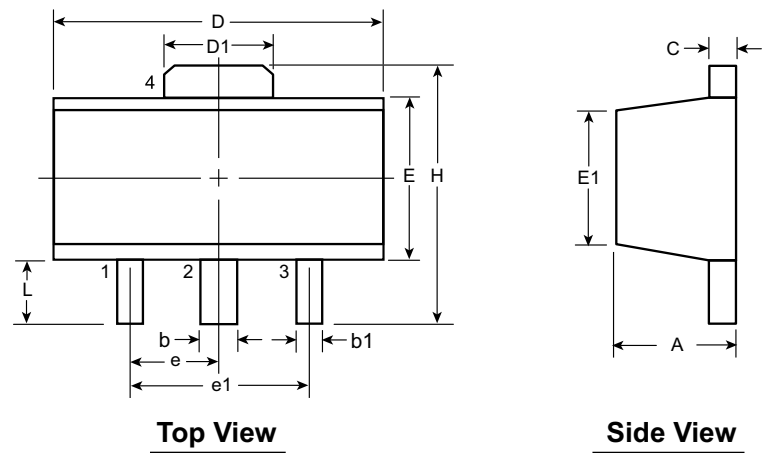
Symbol		A	A1	A2	b	D	E	E1	e	e1	L	L1	θ
Dimension (mm)	MIN	0.89	0.01	0.88	0.30	2.80	2.10	1.20	0.95 BSC	1.90 BSC	0.20 [†]	0.54 REF	0°
	NOM	-	-	0.95	-	2.90	-	1.30			0.50		-
	MAX	1.12	0.10	1.02	0.50	3.04	2.64	1.40			0.60		8°

JEDEC Registration TO-236, Variation AB, Issue H, Jan. 1999.

[†] This dimension differs from the JEDEC drawing.

Drawings not to scale.

3-Lead TO-243AA (SOT-89) Package Outline (N8)



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Symbol		A	b	b1	C	D	D1	E	E1	e	e1	H	L
Dimensions (mm)	MIN	1.40	0.44	0.36	0.35	4.40	1.62	2.29	2.00†	1.50 BSC	3.00 BSC	3.94	0.73†
	NOM	-	-	-	-	-	-	-	-			-	-
	MAX	1.60	0.56	0.48	0.44	4.60	1.83	2.60	2.29			4.25	1.20

JEDEC Registration TO-243, Variation AA, Issue C, July 1986.
† This dimension differs from the JEDEC drawing
Drawings not to scale.

APPENDIX A: REVISION HISTORY

Revision A (April 2017)

- Converted Supertex Doc# DSFP-DN3135 to Microchip DS20005703A
- Changed the packaging format
- Made minor text changes throughout the document

DN3135

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

<u>PART NO.</u>		<u>XX</u>	-	<u>X</u>	-	<u>X</u>
Device		Package Options		Environmental		Media Type
Device:	DN3135	=		N-Channel Depletion-Mode Vertical DMOS FET		
Packages:	K1	=		3-lead SOT-23		
	N8	=		3-lead SOT-89		
Environmental:	G	=		Lead (Pb)-free/RoHS-compliant Package		
Media Type:	(blank)	=		3000/Reel for a K1 Package 2000/Reel for an N8 Package		
Examples:						
a) DN3135K1-G:		N-Channel Depletion-Mode Vertical DMOS FET, 3-lead SOT-23, 3000/Reel				
b) DN3135N8-G:		N-Channel Depletion-Mode Vertical DMOS FET, 3-lead SOT-89, 2000/Reel				

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